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		Filing Date	
		First Named Inventor	Dong Han
		Art Unit	
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U.S. PATENT DOCUMENTS

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中華民國專利公報 (19)(12)

(11) 公告編號：148256

(44) 中華民國79年(1990)12月21日

新型

(51) Int. Cl.: B23Q

全 2 頁

(54) 名稱：平面磨床之工件基準面設定用測定器

(21) 申請案號：79207261 (22) 申請日期：中華民國79年(1990)06月30日

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(57) 申請專利範圍：

1. 一種平面磨床之工件基準面設定用測定器具，為當欲把工件設定在平面磨床時，將該工件基準面設置在正確位置所需之平面磨床之工件基準面設定用測定器具。
其特徵為該測定器具係由基座，與設立於該基座上之支柱，與被該支柱所支持之針盤量規所構成，在上述基座前端部及後端部下方係將周面一部分從基座下面突出而裝設一對圓筒構件，而該圓筒構件係由陶瓷材料所形成，同時，至少該圓筒構件之一邊係被裝設成與上述針盤量規之心軸直交，且該圓筒構件之外周一部分被裝設成從基座先端面突出者。

2. 如申請專利範圍第1項所記載之平面磨床之工件基準面設定用測定器具，其中上述一對圓筒構件係將單一圓筒材料經超精密光製加工之後，加以分割為二者。

3. 如申請專利範圍第1項所記載之平面磨床

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之工件基準面設定用測定器具，其中上述針盤量規係經由連接器以朝上下向滑動自如地安裝在支柱，而在該支柱沿著軸向形成有導溝，同時在上述連接器係在該導溝內設有突出之止轉固定件，又，上述連接器係經由夾鉗螺絲以栓緊／解除自如安裝在支柱，並且，上述針盤量規係經由夾鉗螺絲以栓緊／解除自如地安裝在連接器者。

4. 如申請專利範圍第1、2項任一項所記載之平面磨床之工件基準面設定用測定器具，其中上述圓筒構件之真圓度及真直度係光製成 $1 \mu m$ 以下者。

圖示簡單說明：

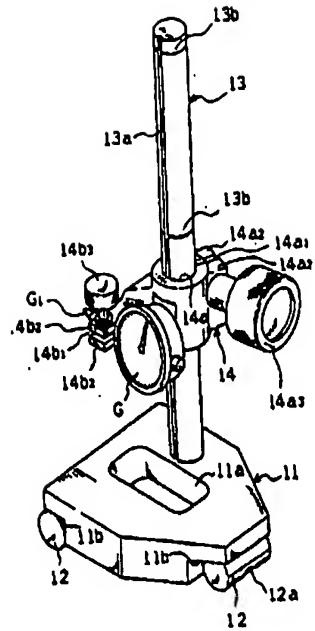
第1圖係全體斜視圖，

第2圖係要部斜視說明圖，

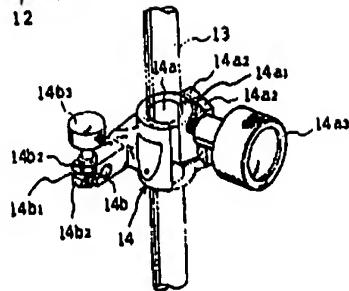
第3圖係第1圖之使用狀態說明圖。

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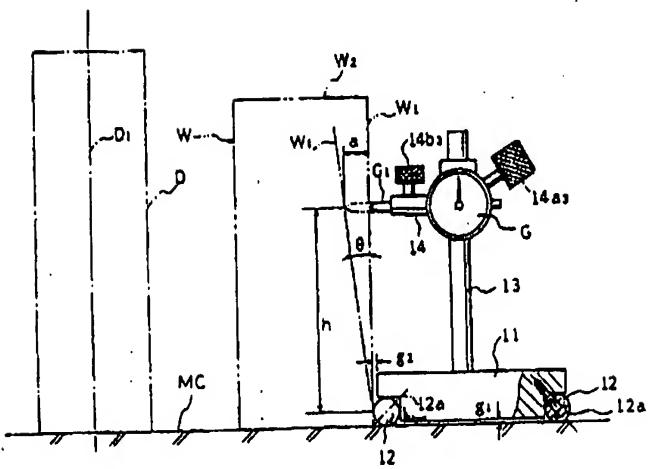
(2)



第1圖



第2圖



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第3圖